

(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property
Organization
International Bureau



(43) International Publication Date
30 September 2004 (30.09.2004)

PCT

(10) International Publication Number
WO 2004/083492 A1

(51) International Patent Classification⁷: C25D 7/12, 5/02

(21) International Application Number:
PCT/KR2004/000586

(22) International Filing Date: 17 March 2004 (17.03.2004)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
10-2003-0016516 17 March 2003 (17.03.2003) KR
10-2003-0016515 17 March 2003 (17.03.2003) KR

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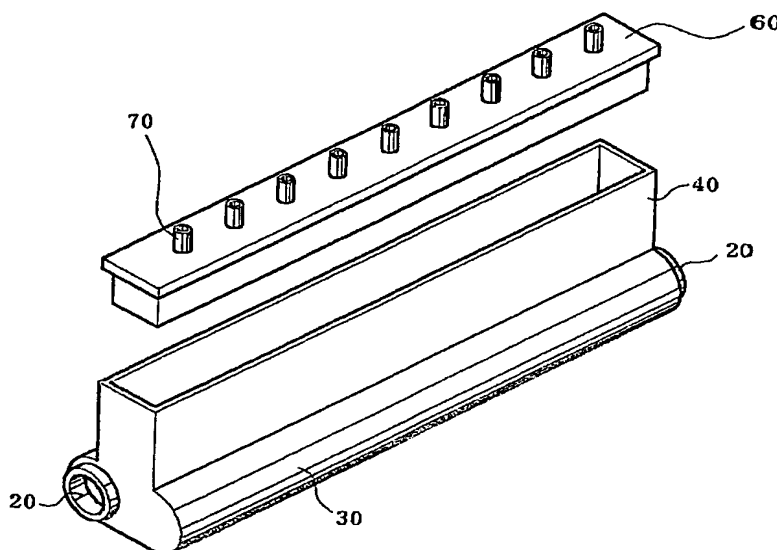
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(81) Designated States (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.

(84) Designated States (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PL, PT, RO, SE, SI, SK,

[Continued on next page]

(54) Title: LEAD FRAME PLATING APPARATUS



(57) Abstract: Disclosed herein is a lead frame plating apparatus. The lead frame plating apparatus comprises side inlets provided in the diagonal direction at opposite sides for supplying plating solution, a flow mixing room defined with an inner space in the longitudinal direction, a plating solution outlet for guiding the plating solution in the direction of nozzles, and a plating solution distribution part provided with the nozzles at an upper part of the plating solution outlet. Each nozzle is provide, at the lower end thereof, with a divergent-shaped expansion tube such that an inner diameter of the inlet of the expansion tube, larger than that of the nozzle, gradually decreases to an extent of the inner diameter of the nozzle. The lead frame plating apparatus supplies the plating solution through the nozzles with a uniform distribution.



TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

Published:

— *with international search report*